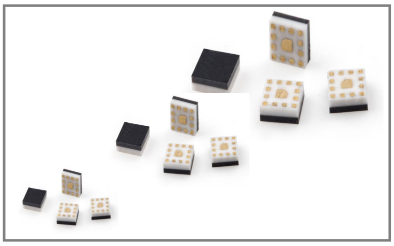
■LTCC 模块

LTCC Modules



◆特征

Feature

- ＊ 优高导热系数
  Excellent thermal conductivity
- ＊ 高密度电路封装
  High density electronic packaging
- ＊ 宽温度使用范围
  Temperature stable
- ＊ LTCC 结构，具备良好的耐湿性、耐腐蚀性、高可靠性
  LTCC construction , and has good moisture resistance, corrosion resistance, high reliability.
- ＊ 符合 RoHS 指令和无卤素要求
  Compliant with RoHS directive and Halogen free requirement.

◆应用

Application

- ＊ 收发组件
  T/R Module
- ＊ 工控类、影像视觉等
  Industrial control 、Camera visual terminal

◆型号表示法

Part Number

SUB	-	3216	4618
①		②	③

① 表示产品代号（3 位数）：“SUB”代表模块

Indicates the product code (3 digits): "SUB" stands for modules.

② 表示产品外形尺寸（4 位数）:如公制 3216 尺寸等。

Indicates the overall dimension of the product (4 digits): such as the metric 3216 size.

③ 表示产品定制化编号（4 位数）：图纸编号等

Represents product customization number (4 digits): Drawing No

◆产品规格尺寸

Product Dimension

- ＊ 可定制化
  Customizable

◆ LTCC 模块使用说明

LTCC modules Instructions for Use

* 尺寸为烧结后成品尺寸;

The dimensions are measured after firing.;

* 可定制化;

Customizable ;

◆ 产品使用注意事项

Precautions on use of products

1、避免采用超过正常额定功率的功率，超过额定功率的稳态负载条件下可能会对产品性能和可靠性产生负面影响。

Avoid applying power exceeding normal rated power, exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

2、用镊子拿起产品时要小心，有可能会将保护或电阻体夹碎。

Be careful when pick up the products with tweezers. There may be a care that the overcoat and other body can be chipped.

3、手动安装产品时，烙铁头勿触碰产品。

Soldering tip shall not touch the product when install product manually.

4、建议贮存条件:温度 5˚C～30˚C，相对湿度 30%～70%。建议在符合上述储存条件下六个月内使用。

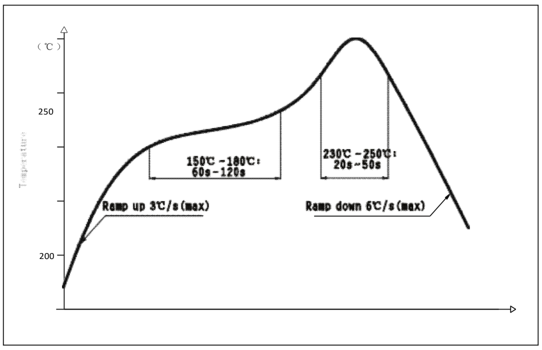
Storage conditions: T: 5℃ ~ 30℃ , RH: 30% ~ 70%.The products are suggested to be used within six months when received, and the storage condition mentioned above should be followed.

5、用于车载设备、医疗设备、航空设备以及其它涉及人身安全、或可能引起重大损失的设备上时，请务必事先与我公司联系。这些产品在这类用途中出现故障或失灵可能导致人身事故或严重损坏。

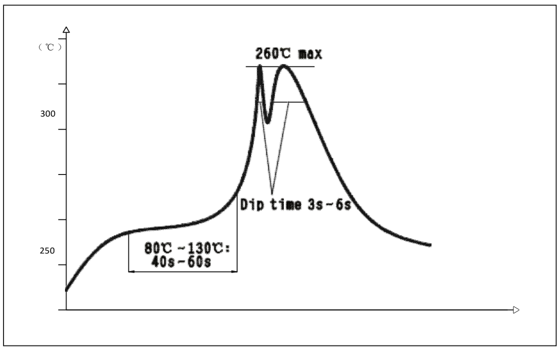
Contact our sales representatives before you use our products for applications including automotive,medical equipment and aerospace equipment. Malfunction or failure of the products in such applications may cause loss of human life or serious damage.

◆ 焊接 Soldering

* 推荐的回流焊曲线 Recommended reflow profile



* 推荐的波峰焊曲线 Recommended wave solder profile



* 推荐的焊膏类型 Recommended solder alloy：96.5Sn/3.0Ag/0.5Cu.